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Chu et al.(10) **Pub. No.: US 2022/0361377 A1**(43) **Pub. Date: Nov. 10, 2022**(54) **IMMERSION COOLING SYSTEM AND
ELECTRONIC APPARATUS HAVING THE
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(57) **ABSTRACT**

An immersion cooling system including a rack and at least one immersion cooling module is provided. The immersion cooling module includes a chassis and a condensation pipeline. The chassis is slidably disposed on the rack and is adapted to accommodate a coolant. At least one heat generating component is adapted to be disposed in the chassis to be immersed in the liquid coolant. The condensation pipeline is disposed in the chassis and is located above the liquid coolant. In addition, an electronic apparatus having the immersion cooling system is also provided.

